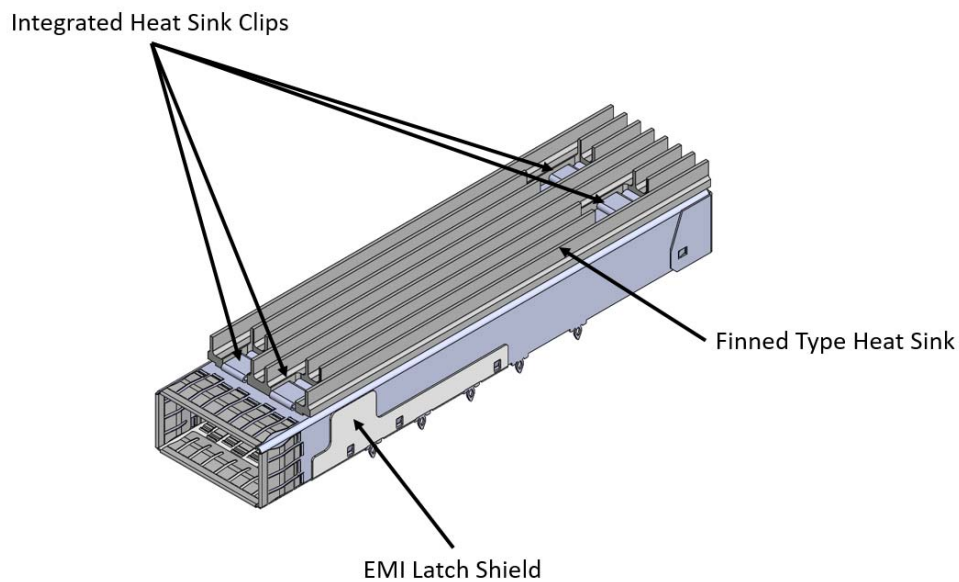


Figure 4-2: EMI Spring Clip

### 4.3.2 Heat Sink Attach Mechanism

A cage and heat sink attached mechanism is shown in Figure 4-3 and Figure 4-4. This cage implementation maximizes the heat sink surface area and the corresponding module heat dissipation. This cage design relies on an integrated heat sink clips at the front and rear of the cage. This approach reduces part count and allows for the use of a heat sink that is the full length of the cage.

This cage design also incorporates an EMI latch shield. This optional shield covers an aperture in the cage due to the latching mechanism resulting in improved shielding performance.

**FIGURE 4-3:** CAGE WITH INTEGRATED HEAT SINK CLIPS AND EMI LATCH SHIELD

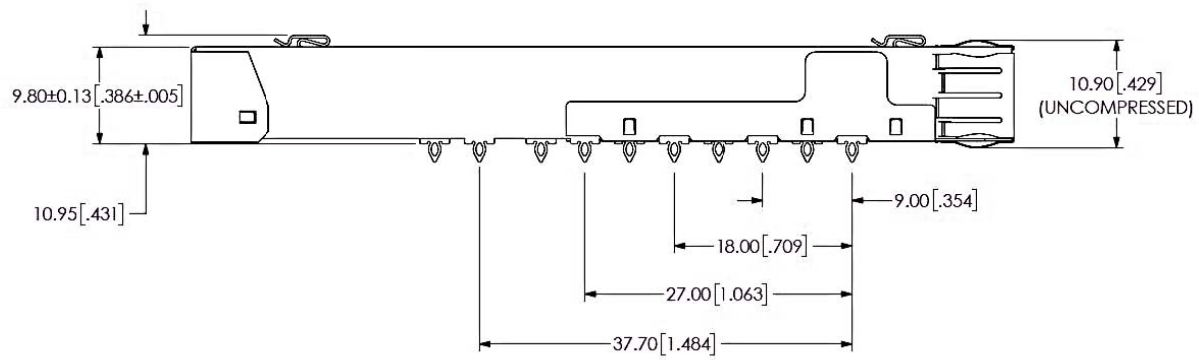


FIGURE 4-4: 1xN CAGE (SIDE VIEW)

### 4.3.3 Host PCB Layout

The features identified in this Annex do not impact the host PCB layout. Footprint compatibility permits the cage implementation in the Annex to be applied in designs with more challenging EMI and thermal objectives.

### 4.3.4 Front Panel Cutout

The EMI spring clip and cage design does not require a change to the front panel cutout allowing for mechanical design compatibility between different cage options.